

Title (en)
HOT WALL RAPID THERMAL PROCESSOR

Title (de)
VORRICHTUNG ZUR SCHNELLEN THERMISCHEN BEHANDLUNG ÜBER AUFGEHEIZTE WÄNDE

Title (fr)
DISPOSITIF DE TRAITEMENT THERMIQUE RAPIDE PAR PAROI CHAUDE

Publication
EP 1226395 A4 20080220 (EN)

Application
EP 00957426 A 20000811

Priority
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Abstract (en)
[origin: WO0113054A1] An apparatus (10) for heat treatment of a wafer (28) is disclosed. The apparatus includes a heating chamber (18) having a heat source (20). A cooling chamber (32) is positioned adjacent to the heating chamber and includes a cooling source (40). A wafer holder (38) is configured to move between the cooling chamber and the heating chamber through a passageway (54) and one or more shutters (52) defines the size of the passageway. The one or more shutters are movable between an open position where the wafer holder can pass through the passageway and an obstructing position which defines a passageway which is smaller than the passageway defined when the shutter is in the open position.

IPC 8 full level
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Citation (search report)
• [X] US 5651670 A 19970729 - OKASE WATARU [JP], et al
• [X] US 5520742 A 19960528 - OHKASE WATARU [JP]
• [XP] US 6056544 A 20000502 - CHO JUN-GEOL [KR]
• [A] US 5908292 A 19990601 - SMITH JOHN Z [US], et al
• See references of WO 0113054A1

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